Preferred Device

Monolithic Dual Switching Diode Common Cathode

• Lead-Free Solder Plating

MAXIMUM RATINGS (EACH DIODE)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	70	Vdc
Forward Current	١ _F	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

THERMAL CHARACTERISTICS

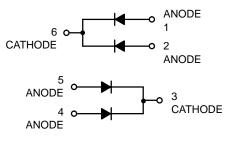
	-	1	
Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 2$	25°C P _D	357	mW
Derate above 25°C		(Note 1) 2.9 (Note 1)	mW/°C
Thermal Resistance - Junction-to-Ambient	$R_{ extsf{ heta}JA}$	350 (Note 1)	°C/W
Characteristic			
(Both Junctions Heated)	Symbol	Max	Unit
· · · · · · · · · · · · · · · · · · ·	Symbol		•
(Both Junctions Heated) Total Device Dissipation T _A = 2	-	500	Unit mW
· · · · · · · · · · · · · · · · · · ·	-		•
Total Device Dissipation $T_A = 2$	-	500 (Note 1)	mW
Total Device Dissipation $T_A = 2$	-	500 (Note 1) 4.0 (Note 1) 250	mW
Total Device Dissipation $T_A = 3$ Derate above 25°C Thermal Resistance -	25°C P _D	500 (Note 1) 4.0 (Note 1)	mW mW/°C

1. FR-4 @ Minimum Pad



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BAV70DXV6T1



SOT-563 CASE 463A PLASTIC

MARKING DIAGRAM



A4 = Specific Device Code

D = Date Code

ORDERING INFORMATION

Device	Package	Shipping
BAV70DXV6T1	SOT-563	4 mm pitch 4000/Tape & Reel
BAV70DXV6T5	SOT-563	2 mm pitch 8000/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

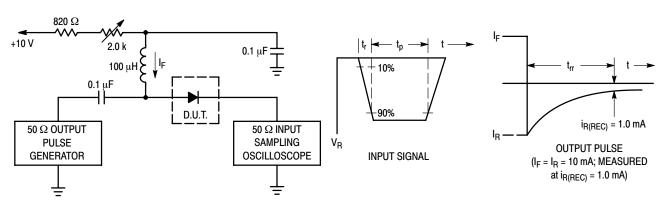
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage (I _(BR) = 100 μAdc)	V _(BR)	70	-	Vdc
Reverse Voltage Leakage Current (Note 4) $(V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C})$ $(V_R = 70 \text{ Vdc})$ $(V_R = 70 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I _R	- - -	60 2.5 100	μAdc
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	C _D	-	1.5	pF
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 50 \text{ mAdc})$ $(I_F = 150 \text{ mAdc})$	V _F	- - - -	715 855 1000 1250	mVdc
$\begin{array}{l} \mbox{Reverse Recovery Time} & \mbox{R}_L = 100 \ \Omega \\ \mbox{(I}_F = I_R = 10 \ \mbox{mAdc}, \ \mbox{V}_R = 5.0 \ \mbox{Vdc}, \ \mbox{I}_{R(REC)} = 1.0 \ \mbox{mAdc}) \ \mbox{(Figure 1)} \end{array}$	t _{rr}	-	6.0	ns

2. 1. FR- 5 = 1.0 \times 0.75 \times 0.062 in.

3. 2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.

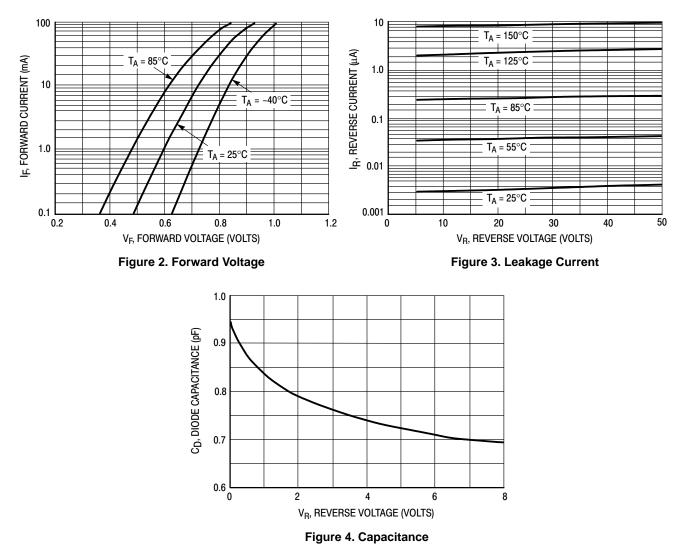
4. 3. For each individual diode while second diode is unbiased.



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA. 3. t_p » t_{rr}

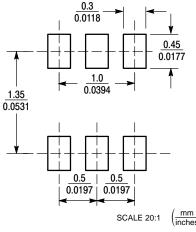
Figure 1. Recovery Time Equivalent Test Circuit

Curves Applicable to Each Anode



INFORMATION FOR USING THE SOT-563 SURFACE MOUNT PACKAGE MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SOT-563

SOT-563 POWER DISSIPATION

The power dissipation of the SOT-563 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A . Using the values provided on the data sheet for the SOT-563 package, P_D can be calculated as follows:

$$P_{D} = \frac{T_{J(max)} - T_{A}}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 150 milliwatts.

$$P_{D} = \frac{150^{\circ}C - 25^{\circ}C}{833^{\circ}C/W} = 150 \text{ milliwatts}$$

The 833°C/W for the SOT-563 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 150 milliwatts. There are other alternatives to achieving higher power dissipation from the SOT-563 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad[®]. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

SOLDERING PRECAUTIONS

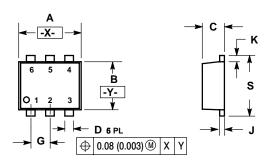
The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A-01 ISSUE O





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.50	1.70	0.059	0.067
В	1.10	1.30	0.043	0.051
С	0.50	0.60	0.020	0.024
D	0.17	0.27	0.007	0.011
G	0.50	BSC	0.020	BSC
J	0.08	0.18	0.003	0.007
Κ	0.10	0.30	0.004	0.012
S	1.50	1.70	0.059	0.067

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHODE 1	PIN 1. COLLECTOR
2. BASE 1	2. EMITTER2	2. CATHODE 1	2. COLLECTOR
COLLECTOR 2	3. BASE 2	ANODE/ANODE 2	3. BASE
EMITTER 2	 COLLECTOR 2 	CATHODE 2	4. EMITTER
5. BASE 2	5. BASE 1	CATHODE 2	5. COLLECTOR
COLLECTOR 1	COLLECTOR 1	ANODE/ANODE 1	6. COLLECTOR

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